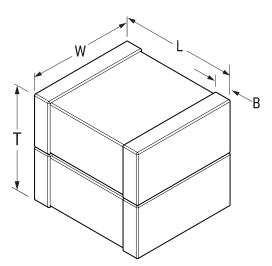




KONNEKT KC-LINK Comm COG, Ceramic, 0.066 uF, 10%, 1,000 VDC, COG, 2-Chip Standard Orientation.



Click	here	for	the	3D	model
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Dimensions	
L	5.7mm +/-0.4mm
W	5mm +/-0.4mm
Т	5mm +/-0.4mm
В	0.6mm +/-0.35mm

Packaging Specifications	
Packaging	T&R, 180mm
Packaging Quantity	300

General Information	
Series	KONNEKT KC-LINK Comm COG
Style	KONNEKT
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss
RoHS	Yes
Termination	Tin
AEC-Q200	No
Typical Component Weight	600 mg
Notes	2-Chip Standard Orientation.
Chip Size	2220-2
MSL	1

Specifications	
Capacitance	0.066 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	1000 VDC
Dielectric Withstanding Voltage	1,200 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	15.1515 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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